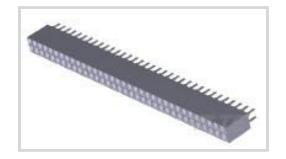


AMPMODU | Modu Connector System

TE Internal #: 8-534206-4 PCB Mount Receptacle, Vertical, Board-to-Board, 68 Position, 2.54 mm [.1 in] Centerline, Gold, Through Hole - Solder, Signal, Modu Connector System

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Receptacle

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: **68**

Number of Rows: 2

Features

Product Type Features

Applied Pressure

PCB Connector Assembly Type

Connector System

connectivity

Standard

PCB Mount Receptacle

Board-to-Board

| Sealable | No |
|-----------------------------------|-----------------------|
| Connector & Contact Terminates To | Printed Circuit Board |
| Configuration Features | |
| Stackable | Yes |
| PCB Mount Orientation | Vertical |
| Number of Positions | 68 |
| Number of Rows | 2 |
| Board-to-Board Configuration | Parallel |
| Electrical Characteristics | |
| Insulation Resistance | 5000 MΩ |
| Operating Voltage | 333 VAC |
| Body Features | |
| Connector Profile | Standard |
| Primary Product Color | Black |
| Contact Features | |

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PCB Mount Receptacle, Vertical, Board-to-Board, 68 Position, 2.54 mm [.1 in] Centerline, Gold, Through Hole - Solder, Signal, Modu Connector System



| Contact Protection Type | Closed Entry Housing |
|--|-------------------------|
| Mating Square Post Dimension | .64 mm[.025 in] |
| | 150 µin |
| Contact Shape & Form | Square |
| PCB Contact Termination Area Plating Material | Tin |
| Contact Base Material | Phosphor Bronze |
| Contact Mating Area Plating Material | Gold |
| Contact Mating Area Plating Material Thickness | .762 μm[30 μin] |
| Contact Type | Socket |
| Contact Current Rating (Max) | 2 A |
| Termination Features | |
| Rectangular Termination Post & Tail Thickness | .2 mm[.008 in] |
| Rectangular Termination Post & Tail Width | .69 mm[.027 in] |
| Termination Post & Tail Length | 2.92 mm[.115 in] |
| Termination Method to Printed Circuit Board | Through Hole - Solder |
| Mechanical Attachment | |
| Mating Alignment | Without |
| PCB Mount Retention | Without |
| PCB Mount Alignment | Without |
| Connector Mounting Type | Board Mount |
| Housing Features | |
| Mating Entry Location | Тор |
| Centerline (Pitch) | 2.54 mm[.1 in] |
| Housing Material | Polyester - GF |
| Dimensions | |
| Connector Height | 5.03 mm[.198 in] |
| Row-to-Row Spacing | 2.54 mm[.1 in] |
| Stack Height | 10.92 mm[.43 in] |
| PCB Thickness (Recommended) | 1.57 mm[.055 – .094 in] |
| Jsage Conditions | |
| Housing Temperature Rating | Standard |
| | |

PCB Mount Receptacle, Vertical, Board-to-Board, 68 Position, 2.54 mm [.1 in] Centerline, Gold, Through Hole - Solder, Signal, Modu Connector System



Operation/Application

| Solder Process Feature | Board Standoff |
|---|--|
| Circuit Application | Signal |
| Industry Standards | |
| Approved Standards | CSA LR7189, UL E28476 |
| UL Flammability Rating | UL 94V-0 |
| Packaging Features | |
| Packaging Quantity | 6 |
| Packaging Type | Box, Tube |
| | |
| Product Compliance | |
| For compliance documentation, visit the product page on TE.com> | |
| EU RoHS Directive 2011/65/EU | Compliant |
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) |

2023 (235) Does not contain REACH SVHC

Not Low Halogen - contains Br or Cl > 900 ppm.

Solder Process Capability

Halogen Content

Wave solder capable to 240°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

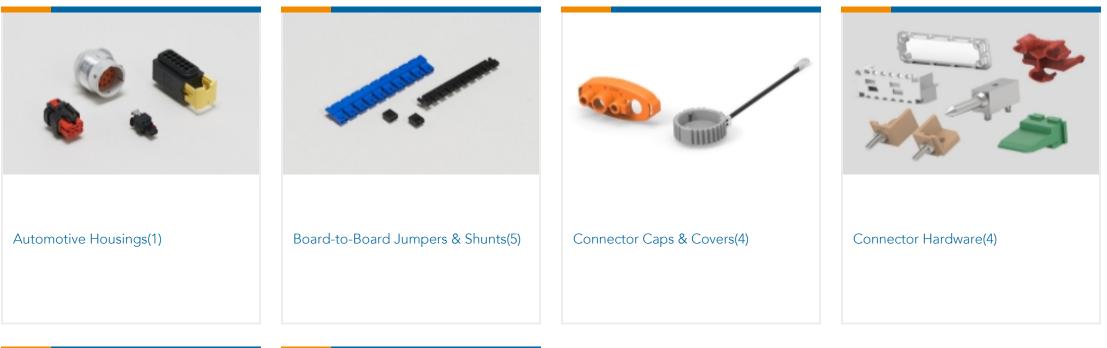
Compatible Parts

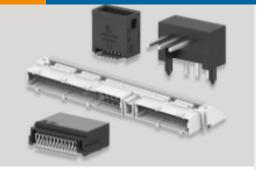
PCB Mount Receptacle, Vertical, Board-to-Board, 68 Position, 2.54 mm [.1 in] Centerline, Gold, Through Hole - Solder, Signal, Modu Connector System



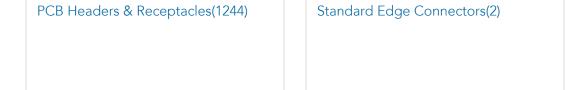


Also in the Series | Modu Connector System

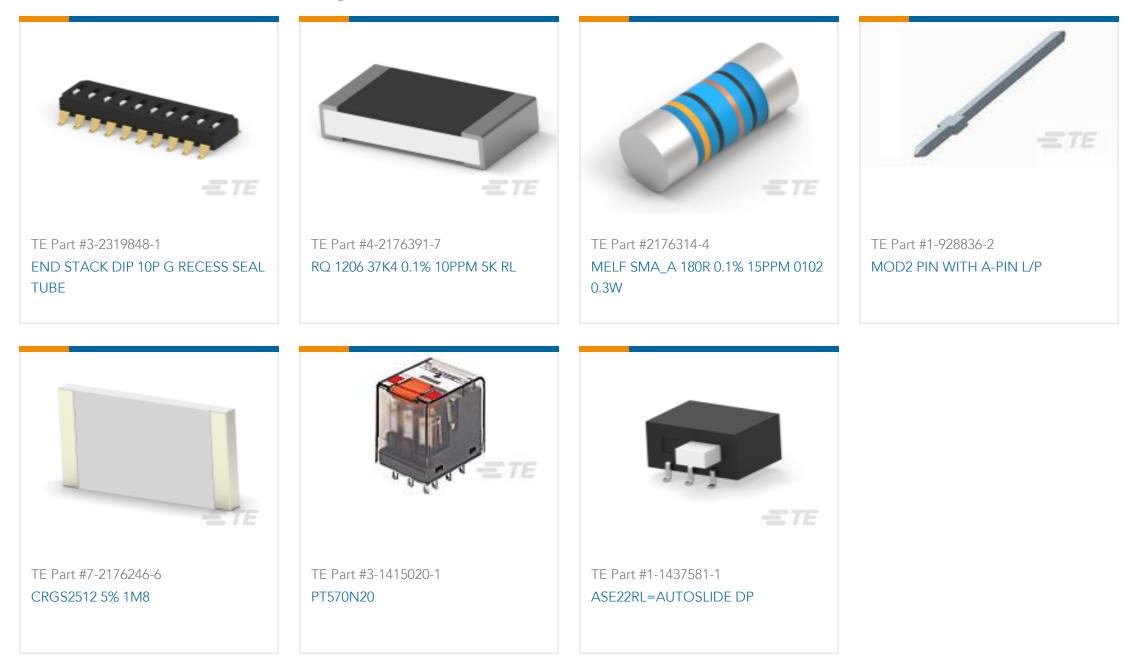








Customers Also Bought



PCB Mount Receptacle, Vertical, Board-to-Board, 68 Position, 2.54 mm [.1 in] Centerline, Gold, Through Hole - Solder, Signal, Modu Connector System



Documents

Product Drawings 68 MODII VRT DR CE 100/115

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_8-534206-4_N.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_8-534206-4_N.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_8-534206-4_N.3d_stp.zip

English

By downloading the CAD file I accept and agree to the Terms and Conditions of use.

Product Specifications Application Specification

English